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an open-circuit voltage (Voc) of the solar cell 100. Accordingly, the open-circuit voltage and the short-circuit current of the solar cell 100 can be increased by the anti-reflection layer 22, and thus, the efficiency of the solar cell 100 can be enhanced.

The anti-reflection layer 22 may include one or more of various materials. For example, the anti-reflection layer 22 may include a silicon nitride layer. However, the invention is not limited thereto. Thus, the anti-reflection layer 22 may have a single film structure or a multi-layer film structure including, for example, at least one material selected from a group including silicon nitride, silicon nitride including hydrogen, silicon oxide, silicon oxy nitride, MgF₂, ZnS, TiO₂ and CeO₂.

The first electrode 24 is electrically connected to the emitter layer 20 by penetrating the anti-reflection layer 22 at the front surface of the semiconductor substrate 10. The first electrode 24 in plan view may have various shapes. For example, as shown in FIG. 2, the first electrode 24 may include a plurality of finger electrodes 24a. The finger electrodes 24a are parallel to each other and are spaced apart from each other with a first distance D1. Also, the first electrode 24 may include a bus bar electrode 24b extending in a direction crossing the finger electrodes 24a to connect to the finger electrodes 24a. The bus bar electrode 24b may include a single bus bar electrode 24b, or the bus bar electrode 24b may include a plurality of bus bar electrodes 24b as shown in FIG. 2. The plurality of bus bar electrodes 24b are spaced apart from each other with a second distance D2 that is larger than the first distance D1. Here, a width W1 of the finger electrode 24a may be smaller than a width W2 of the bus bar electrode 24b. However, the invention is not limited thereto, and thus, the width W1 of the finger electrode 24a may be the same as the width W2 of the bus bar electrode 24b. That is, the shape of the first electrode 24 is described as an example, and thus, the invention is not limited thereto. Also, the first electrode 24 may include one or more of various materials.

Referring to FIG. 1 again, the back surface field layer 30 of the second conductive type is formed at the back surface of the semiconductor substrate 10. Here, the back surface field layer 30 may include a second dopant 302 of the second conductive type and a second counter dopant 304 of the first conductive type opposite to the second conductive type.

An n-type dopant such as a group V element (for example, phosphorus (P), arsenic (As), bismuth (Bi), antimony (Sb), or the like) may be used for the second dopant 302. A p-type dopant such as a group III element (for example, boron (B), aluminum (Al), gallium (Ga), indium (In) or the like) may be used for the second counter dopant 304. However, the invention is not limited thereto, and thus, the second dopant 302 and the second counter dopant 304 may be formed of one or more of various elements or materials.

In the embodiment, the back surface field layer 30 as the dopant layer includes the second counter dopant 304, along with the second dopant 302. Accordingly, the back surface field layer 30 can have a sufficient thickness, and the recombination velocity can be reduced by decreasing the surface concentration of the back surface field layer 30.

For example, the back surface field layer 30 may have sheet resistance of about 50~150 ohm/square (ohm/□), and may have a thickness of about 0.3~1.5 μm (for example, 0.5~1.2 μm). However, the invention is not limited thereto. Thus, the sheet resistance and the thickness of the back surface field layer 30 may be changed.

Here, a doping concentration of the second counter dopant 304 is less than a doping concentration of the second dopant 302, and the back surface field layer 30 has the second con-

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ductive type. For example, the ratio of the doping concentration of the second counter dopant 304: the doping concentration of the second dopant 302 may be about 1:3 to 1:30. When the ratio is above 1:30, the reduction of the surface concentration due to the second counter dopant 304 may be small. When the ratio is below 1:3, the property of the back surface field layer 30 may be deteriorated. Here, when the ratio of the doping concentration of the second counter dopant 304: the doping concentration of the second dopant 302 is about 1:5 to 1:15, the second counter dopant 304 has a great effect.

The concentration difference between the second counter dopant 304 and the second dopant 302 may originate in a doping amount difference between the second counter dopant 304 and the second dopant 302. In this case, the doping amount of the second counter dopant 304 and the second dopant 302 can be detected by secondary ion mass spectroscopy and so on.

The passivation layer 32 and the second electrode 34 may be formed at the back surface of the semiconductor substrate 10.

The passivation layer 32 may be substantially at the entire back surface of the semiconductor substrate 10, except for the portions where the second electrode 34 is formed. The passivation layer 32 passivates defects at the back surface of the semiconductor substrate 10, and eliminates the recombination sites of minority carrier. Thus, an open circuit voltage (Voc) of the solar cell 100 can be increased.

The passivation layer 32 may include a transparent insulating material for passing light. Thus, the light can be incident to the back surface of the semiconductor substrate 10 through the passivation layer 32, and thereby enhancing the efficiency of the solar cell 100. The passivation layer 32 may have a single film structure or a multi-layer film structure including, for example, at least one material selected from a group including silicon nitride, silicon nitride including hydrogen, silicon oxide, silicon oxy nitride, MgF₂, ZnS, TiO₂ and CeO₂. However, the invention is not limited thereto, and thus, the passivation film 32 may include one or more of various materials.

The second electrode may include a metal having a high electric conductivity. Also, the second electrode 34 may have a structure similar to the structure of the first electrode 24 shown in FIG. 2, and thus, the descriptions of the detailed structure of the second electrode 34 will be omitted.

Likewise, the emitter layer 20 includes the first dopant 202 and the first counter dopant 204, and the back surface field layer 30 includes the second dopant 302 and the second counter dopant 304. Accordingly, each of the emitter layer 20 and the back surface field layer 30 can have sufficient thicknesses, and the recombination velocity can be reduced by decreasing the surface concentration of the emitter layer 20 and the back surface field layer 30. Accordingly, the efficiency of the solar cell 100 can be maximized. In the above embodiment, the semiconductor substrate 10 and the back surface field layer 30 have the n-type dopant for the second dopant 302, and the emitter layer 20 has the p-type dopant for the first dopant 202. However, the present invention is not limited thereto. Therefore, it is possible that the semiconductor substrate 10 and the back surface field layer 30 have the p-type dopant for the second dopant 302 and the emitter layer 20 has the n-type dopant for the first dopant 202.

Also, in the above embodiment, the emitter layer 20 includes the first counter dopant 204 and the back surface field layer 30 includes the second counter dopant 304. However, the present invention is not limited thereto. Thus, it is possible that the emitter layer 20 includes the first counter dopant 204 and the back surface field layer 30 does not